Using TCAD to understand GaN design dependencies for Electric Vehicle applications

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Bodo's Wide Bandgap Event 2024 Making WBG Designs Happen

## Agenda Topics

Typical EV Architecture

- Electric Vehicle trends and performance challenges
- TCAD for GaN design : How it is used today
- ► Extending TCAD : Introducing FTCO<sup>TM</sup>



Source : PowerElectronics Tips





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Source : Spectrum Logic

## The EV Problem to be Solved

- Market demand has slowed : Pressure is on EV Manufacturers on Cost, Quality and Usability
- ► GaN can play a vital role in optimizing EV Performance

Car	Battery (kWh)	Range (km)	Performance (km/kWh)	Cost per mile
Tesla Model 3	57.5	416	7.23	6.18p
Hyundai Ioniq	77.4	488	6.59	6.80p
Vauxhall Corsa	51.0	312	6.48	6.92
Dacia Spring	26.8	160	6.40	7.00
Fiat 500e	24.0	136	6.36	7.03
BMW i4 eDrive40	83.9	512	6.35	7.06
Peugeot e-208	51.0	304	6.32	7.08
Mini Cooper E	37.0	232	6.27	7.14



Tesla Model 3



Dacia Spring Electric 45



BMW i4 eDrive 40

Source : cargurus.co.uk 2024

## Optimizing for Efficiency

- Our generation has been extravagant with energy resources...
- Environmental arguments, and tax incentives encourage all us to buy Electric Vehicles
- But there is market anxiety : Range, Infrastructure, Depreciation, ReCycling
- GaN based power converters can give is a further few % points of energy efficiency

	Si	GaAs	4H-SiC	GaN
Bandgap (eV)	1.12	1.43	3.26	3.4
Breakdown field (10 <sup>6</sup> V/cm)	0.3	0.3	2.5	3.0
Thermal conductivity (W/cm/K)	1.5	0.5	4.5	1.5
Saturated velocity (10 <sup>7</sup> cm/sec)	1.0	1.0	2.0	1.5
Electron mobility (cm <sup>2</sup> /V/sec)	400	4000	500	1800
Hole mobility (cm <sup>2</sup> /V/sec)	480	400	110	150
Dielectric constant	11.9	13.1	10	10.4

#### **Energy Efficiency:**

- Internal Combustion : 20-30%
- Electric Vehicle : 75-80%



Source JD Power

## TCAD is an essential starting point for GaN design

TCAD allows designers to investigate design options, and predict device behavior



## GaN : Multiple Design Variables

#### Designers can investigate dependencies and improve understanding using TCAD



- Contacts
- Shields
- GaN Buffer



- Molar Concentration
- Impurities











Aluminum Aluminum Silicon Si

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Nitrogen

- RDS On
- Thermal Conductivity
- Gate Capacitance
- Charge Density
- **Blocking Voltage**
- Parasitics
- Transient Switching



## Extending TCAD with Design of Experiments (DOE)

- Test Example : Lateral AlGaN/GaN HEMT
  - Optimize BV and RDSON
- Use DOE to identify the variables with high influence
- Use ML to analyze the data and match the simulation to the actual device





"Breakdown voltage improvement of enhancement mode AlGaN/GaN HEMT by a novel stepetched GaN buffer structure" Hao Wu, Xiaojun Fu, Yuan Wang, Jingwei Guo, Jingyu Shen, Shengdong Hu# <u>https://doi.org/10.1016/j.rinp.2021.104768</u>

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## **GaN Parameter Analysis**

Experiment with the GaN Design Variables

► A collection of simulation results is assembled, with analysis of the most critical variables

	Init	Low	High
scf_GaN	0.6	0.36	0.84
scf_AlGaN	2.1	1.26	2.94
piezo_sc	0.65	0.39	0.91
lev_acc	2.85	1.71	3.99
d_acc	1.000e+17	6e+16	1.4e+17
sig_acc	1.000e-15	6e-16	1.4e-15
lev_don	0.5	0.3	0.7
d_don	2.000e+17	1.2e+17	2.8e+17
sig_don	1.000e-15	6e-16	1.4e-15
lev_Mg	0.16	0.096 0.224	
d_Mg	3.000e+18	1.8e+18	4.2e+18
sig_Mg	1.000e-13	6e-14	1.4e-13
d_int	1.500e+19	9e+18	2.1e+19
lev_int	0.3	0.18	0.42
sig_int	5.000e-14	3e-14	7e-14





## Extend the process to include Manufacturing : FTCO™

Gain deep manufacturing variables and improve quality and yield

- Design Targeting:
  - Provide design targets, define design inputs
  - "Digital Twin" model returns input values to achieve the targets
- More efficient, more precise specification
- Determines dominant inputs to rapidly understand and optimize technology
- What does the designer really need to worry about?





## Machine Learning algorithm generates Digital Twin

Digital Twin can be used by Fab engineers to improve yield and quality

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Optimized Digital Twin

## FTCO<sup>™</sup> : Amalgamated TCAD, Fab and Digital Twin Data



- Measurement data from fab-out wafers (electrical)
- Measurement data from in-line metrology (structural)
- Device Modeling (TCAD, SPICE) Target Optimization
- Reduce cost of manufacturing / improve time to market
- Fewer wafer runs, failed trials
- More productive use of TCAD

## AESIN : Automotive Innovation with Power Electronics (UK)

Supplier Collaboration for Automotive EV

- Compound Semiconductor Research
- Innovative Inverter Designs, Higher Switching Speeds
- Thermal Modelling and Packaging
- High Frequency performance, smaller magnetics, EMF
- ► Failure Modes, Short-Circuits, Aging Models
- Power Train Design
- ► EV ECUs (OBC, Traction Drive Controllers, SDV Controls)

https://aesin.org.uk/





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## Summary

Silvaco FTCO<sup>™</sup> – Optimizing Power Semiconductor Devices

- ► WBG Materials such as GaN are complex to analyze
- Simulation data from TCAD together with harvested Manufacturing data can now be included in the design process (FTCO<sup>TM</sup>)
- Improved GaN devices mean more efficient EV energy conversion
- ► GaN-based inverters are already being adopted for OBC, BMS applications in EVs

Please check our web site for more information : <u>www.silvaco.com</u>

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# Thank you. SILVACO



### Abstract

Optimizing the use of the available energy-budget in Electric Vehicle design has become a top objective for vehicle manufacturers, and their requirements ripple down the automotive supply chain.

The Benefits of GaN switching devices in automotive power applications are well documented, but how far can these devices be further adapted and improved to win wider adoption in automotive applications?

This presentation will look at the demands of the automotive industry, and the role of TCAD (Technology Computer Aided Design), and FTCO (Fab Technology Co-Optimization) tools in the GaN device design process.

By combining manufacturing data, actual device measurements, and simulation results into the design flow, engineers can maximize GaN device quality and performance.

Compromise on design parameters is application-specific

